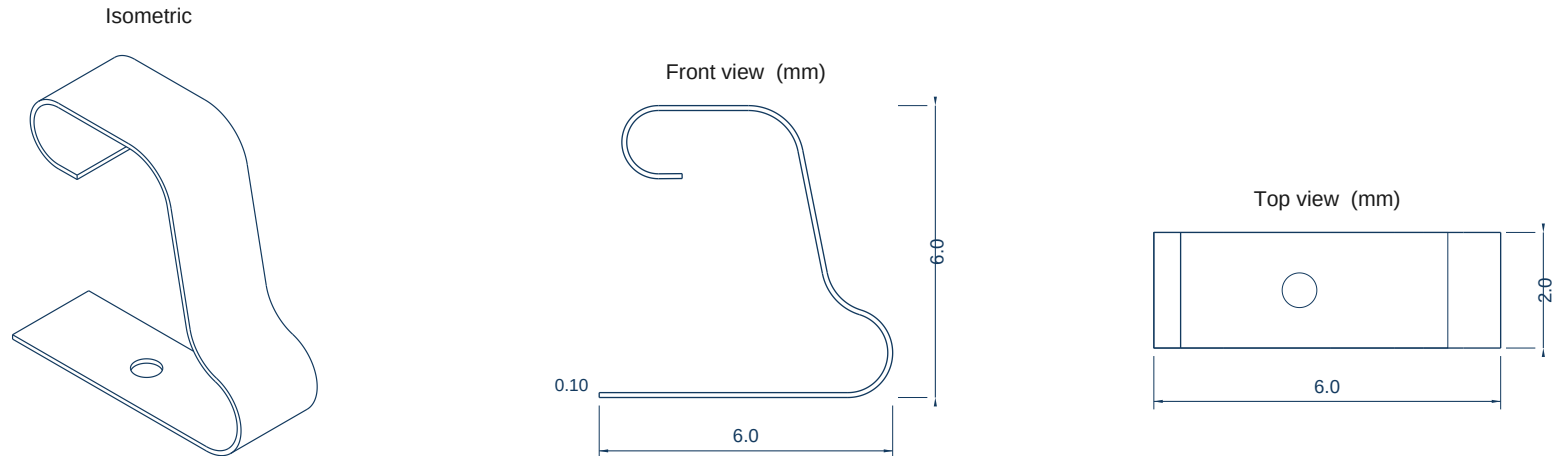




Type C-11 BC11-20060060

SMD EMI Spring Contact | Beryllium Copper | Units: mm



MECHANICAL

VALUE

Thickness	0.10 mm
Width	2.0 mm +/- 0.2
Length	6.0 mm +/- 0.2
Height	6.0 mm +/- 0.2
Form	base plate, S-bend riser, top arm, curled end hook
S-bend	R0.864 CL, 163 deg then R1.055 CL, 62 deg
Top bend	R1.084 CL, 79 deg
End hook	R0.697 CL, 180 deg
Riser	2.55 mm
Base hole	dia 0.60 mm at 2.52 from the base end
Developed length	17.24 mm
Material / plating	BeCu, Gold-plated (G)
Volume / mass	3.419 mm ³ 28.6 mg (BeCu)

PRODUCT DATA

VALUE

Mfr P/N	BC11-20060060G-SY (Au)
Brand	Seyunda
Description	SMD EMI Contact 6.0x2.0x6.0mm Au
Packaging	Tape & Reel (TR)
Category	Connectors, Interconnects
Sub-category	Contacts, Spring Loaded (Pogo Pins), and Pressure
Lifecycle / origin	Active / Taiwan, Republic of China
RoHS / REACH	RoHS3 Compliant / REACH Unaffected
ECCN / ESD	EAR99 / Static sensitive: Yes
Datasheet	seyunda.com/datasheet/Seyunda-SMD-Spring-Contacts-Datasheet.pdf
Product page	seyunda.com/type-c-11.html
File format	STEP AP214